

Form PTO-1449

Docket Number (Optional)

Applying Number

MEG-00-009B

10/614, 928

Applicant

Jin-Yuan Lee

Filing Date

07/08/03

Drawn At Unit

INFORMATION DISCLOSURE CITATION
IN AN APPLICATION

(Use several sheets if necessary)

U. S. PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	ALSO DATE IF APPROPRIATE
DM 5811351	9/22/98	Kawakita et al.	438	613	11/25/97
DM 5422435	6/6/95	Takiar et al.	174	52.4	5/22/92
DM 5994166	11/30/99	Akram et al.	438	108	3/10/97
DM 5952725	9/14/99	Ball	257	777	1/17/97
DM 5608262	3/4/97	Degani et al.	257	723	2/24/95

FOREIGN PATENT DOCUMENTS

DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	Translation YES NO

OTHER DOCUMENTS (Including Author, Title, Date, Portion of Pages, Etc.)

DM	Article, published as part of the 2000 Electronic Components and Tech. Conf. of 05/21/00 - 05/24/00, by Jean Dufresne, "Hybrid Assembly Technology for Flip-Chip-on-Chip (FCOC) Using PBGA Laminate Assembly," Ref. # 0-7803-5908-9/00, IEEE.

EXAMINER

DATE CONSIDERED

2/18/05

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP § 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.